



73

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PRELIMINARY AMENDMENT ACCOMPANYING SUBMISSION OF MISSING PARTS

APPLICANT: Akira Yoshizawa, et al.

ATTY. DOCKET NO. 09792909-5237

SERIAL NO.

DATE FILED:

INVENTION: "SEMICONDUCTOR DEVICE USING INTERPOSER SUBSTRATE AND
MANUFACTURING METHOD THEREFOR"

Assistant Commissioner of Patents
Washington, D.C. 20231

S I R:

Applicants submit this Preliminary Amendment for consideration in the above-identified
patent application:

IN THE SPECIFICATION

At page 10, line 16, change "Figs. 4A to 4F" to --Figs. 4A to 4J--.

Respectfully submitted,

(Reg. No. 32,919)

David R. Metzger
SONNENSCHN NATH & ROSENTHAL
P.O. Box #061080
Wacker Drive Station
Sears Tower
Chicago, IL 60606-1080
Customer #26263

Attorneys for Applicant(s)

2004120 "E6502660

FIG. 4A

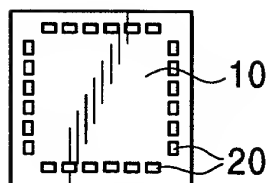


FIG. 4B

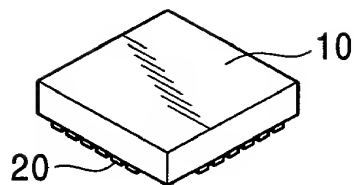


FIG. 4C

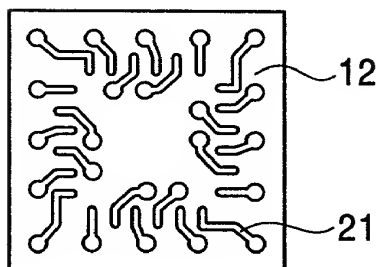


FIG. 4D

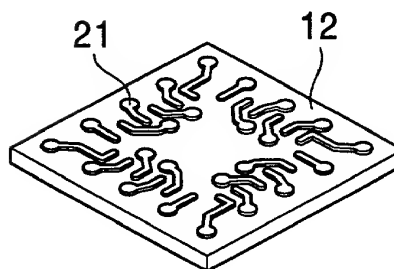


FIG. 4E

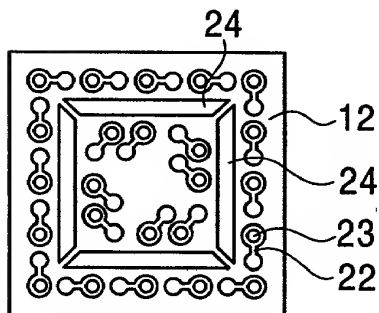


FIG. 4F

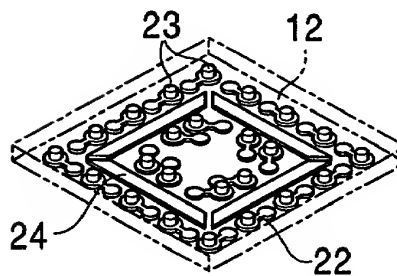


FIG. 4G

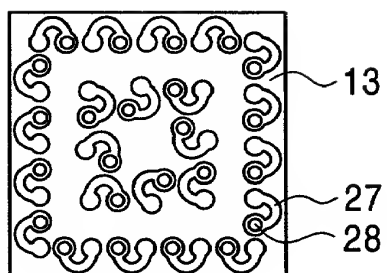


FIG. 4H

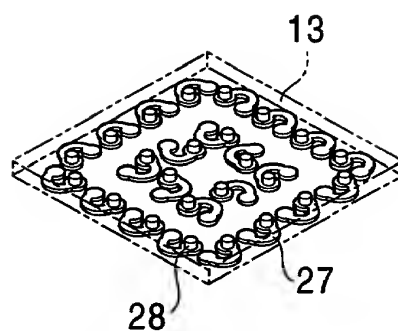


FIG. 4I

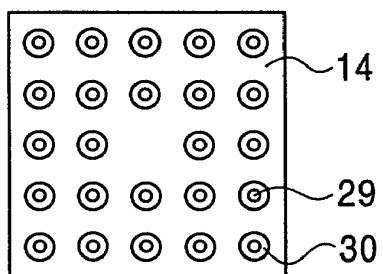


FIG. 4J

